

Amendments to the Claims

Claims 1-104 (Cancelled).

105. (Currently amended) A method of forming an insulative material adjacent a conductive electrical component comprising:

providing an initial material adjacent the conductive electrical component, the initial material comprising pores having a size and comprising a mixture of carbon and SiC_x, the providing comprising depositing carbon utilizing plasma decomposition of at least one precursor compound ~~molecules consisting of silicon and carbon;~~

forming a layer overlying the initial material ~~mass~~; and

decreasing the dielectric constant of the initial material to form the insulative material by vaporizing a portion of the initial material to expand the size of the pores.

Claims 106-110. (Cancelled).

111. (Currently amended) The method of Claim 105, ~~further~~ comprising forming ~~a layer over~~ the layer overlying the initial material before the vaporizing.

112. (Currently amended) The method of Claim 105, ~~further~~ comprising forming ~~a layer over~~ the layer overlying the initial material after the vaporizing.

113. (Previously presented) The method of Claim 105, where the conductive electrical component comprises a pair of conductive lines.

114. (Previously presented) The method of Claim 113, further comprising forming at least one support member between the pair of conductive lines.

Claims 115-129. (Cancelled)

130. (Currently amended) The method of claim 105 wherein the initial material comprises from about 20% to about 80% SiC_x, by volume.

131. (New) The method of claim 105 wherein the at least one precursor comprises a member of the group consisting of C_nH_{2n} and C_nH_{2n}X_n, where X is a halogen.

132. (New) The method of claim 105 wherein the layer overlying the initial material comprises a gas permeable insulative material.